

ARRAY-TYPE MEGASONIC CLEANING DEVICE FOR CLEANING WAFERS

ABSTRACT

An array-type megasonic cleaning device for cleaning wafers (5), comprising: a washing tank (3); and a first driving shaft (1) and a second driving shaft (2) that are arranged in parallel with each other in the cleaning tank (3), are capable of rotating circumferentially about their own center axes under the drive of a drive unit (4) and have an axial length of 60-350 mm, wherein at least two first engaging grooves (11) are formed on the first driving shaft (1) in a length direction, at least two second engaging grooves (21) are formed on the second driving shaft (2) in a length direction, and the second engaging grooves (21) are arranged corresponding to the first clamping grooves (11); the plurality of wafers (5) are respectively placed by means of the cooperation between the first engaging grooves (11) and the second engaging grooves (21); and the first driving shaft (1) and the second driving shaft (2) rotate in the same direction, and the plurality of wafers (5) can be driven by friction to rotate simultaneously, so as to achieve the effect of cleaning. With this arrangement, a plurality of wafers (5) can be placed in the cleaning tank (3) for simultaneous cleaning, so as to minimize the footprint of the cleaning tank (3) to the greatest extent and ensure the consistency of the cleaning effect of the wafers (5) under the premise of ensuring the same cleaning efficiency.

FIG. 1